

SEMICONDUCTOR

FMBSA56

PNP General Purpose Amplifier

- This device is designed for general purpose amplifier applications at collector currents to 300 mA.
- Sourced from Process 73.



SuperSOTTM-6 single Mark: .2G1

Absolute Maximum Ratings* T_a=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V _{CEO}	Collector-Emitter Voltage	-80	V
V _{CBO}	Collector-Base Voltage	-80	V
V _{EBO}	Emitter-Base Voltage	-4.0	V
l _C	Collector Current - Continuous	-500	mA
T _J , T _{STG}	Operating and Storage Junction Temperature Range	- 55 ~ 150	°C

* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:

These ratings are based on a maximum junction temperature of 150 degrees C.
These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Electrical Characteristics T_a=25°C unless otherwise noted

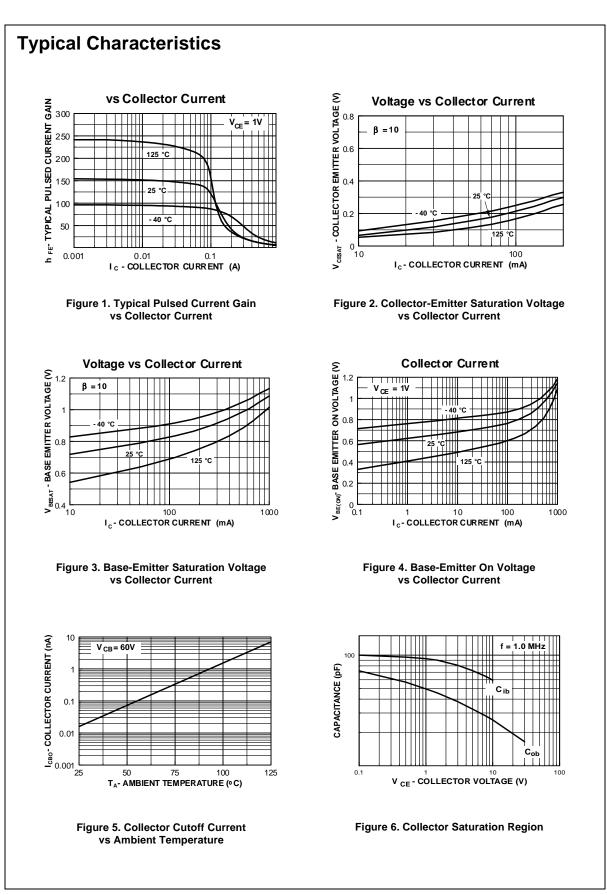
Symbol	Parameter	Test Condition	Min.	Max.	Units
Off Characte	eristics		•		
V _{(BR)CEO}	Collector-Emitter Sustaining Voltage *	$I_{\rm C} = -1.0 {\rm mA}, I_{\rm B} = 0$	-80		V
V _{(BR)CBO}	Collector-Base Breakdown Voltage	$I_{\rm C} = -100 \mu A, I_{\rm E} = 0$	-80		
V _{(BR)EBO}	Emitter-Base Breakdown Voltage	$I_{\rm E} = -100 \mu A, I_{\rm C} = 0$	-4.0		V
I _{CEO}	Collector Cut-off Current	$V_{CE} = -60V, I_B = 0$		-0.1	μΑ
I _{CBO}	Collector Cut-off Current	$V_{CB} = -80V, I_E = 0$		-0.1	μΑ
On Characte	eristics				
h _{FE}	DC Current Gain	I _C = -10mA, V _{CE} = -1.0V	100		
		I _C = -100mA, V _{CE} = -1.0V	100		
V _{CE(sat)}	Collector-Emitter Saturation Voltage	I _C = -100mA, I _B = -10mA		-0.25	V
V _{BE(on)}	Base-Emitter On Voltage	I _C = -100mA, V _{CE} = -1.0V		-1.2	V
Small Signa	I Characteristics				
f _T	Current Gain Bandwidth Product	$I_{\rm C} = -10$ mA, $V_{\rm CE} = -2.0$ V,	50		MHz
		f = 100MHz			

* Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2.0%

Thermal Characteristics T_a=25°C unless otherwise noted

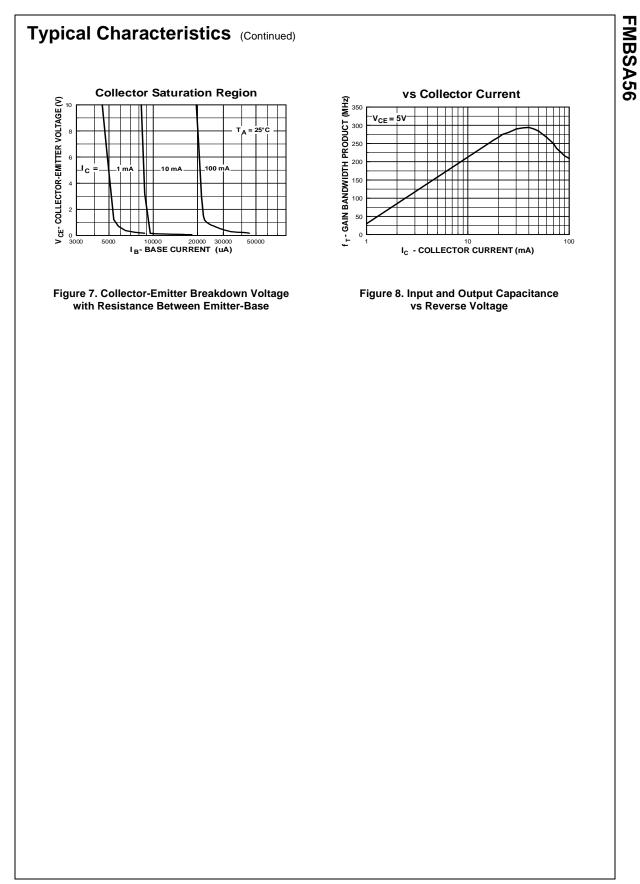
Symbol	Parameter	Max.	Units
PD	Total Device Dissipation *	700	mW
$R_{ extsf{ heta}JA}$	Thermal Resistance, Junction to Ambient, total	180	°C/W

Device mounted on a 1 in 2 pad of 2 oz copper.

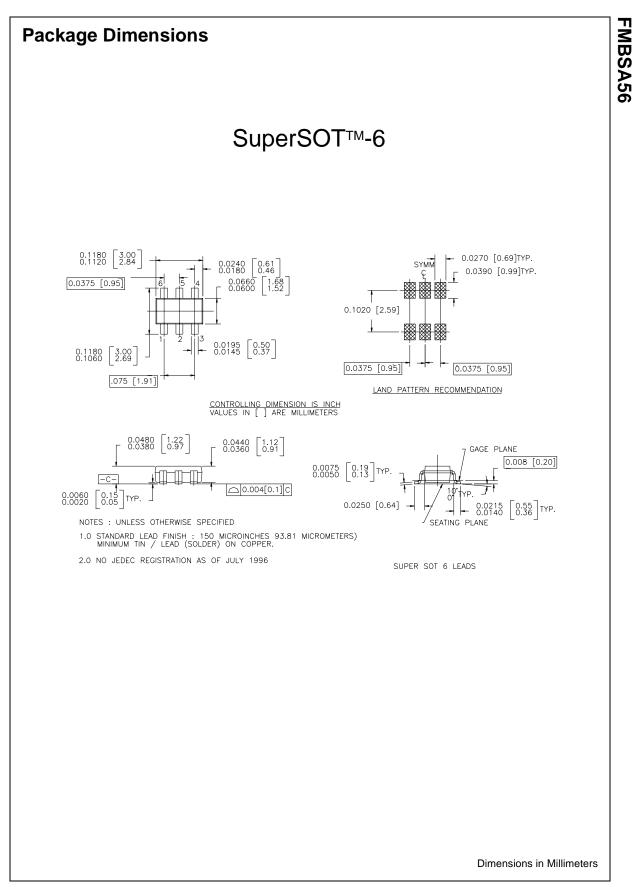


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Definition of Terms

Datasheet Identification	Product Status	Definition
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Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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